

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	microeletronic and die and (no-flow adj underfill adj material) and wet and assembling and assembled and preheating and carrier	USPAT	OR	ON	2004/11/15 17:43
L2	0	microelectronic and die and (no-flow adj underfill adj material) and wet and assembling and assembled and preheating and carrier	USPAT	OR	ON	2004/11/15 17:43
L3	3	microelectronic and die and (no-flow adj underfill adj material)	USPAT	OR	ON	2004/11/15 17:43
L4	3	3 and (wetting or wet or characterictic or improved or assembled or assembling or no-flow or underfill or material or allowing or construction or reflowing or reflow or time or period or temperature or preheat or preaheating or harden or sufficient or microelectronic or die or chip or integrated or circuit or carrier)	USPAT	OR	ON	2004/11/15 18:06
L5	3	3 and (wetting or wet or characterictic or improved or assembled or assembling or no-flow or underfill or material or allowing or construction or reflowing or reflow or time or period or temperature or preheat or preaheating or harden or sufficient or microelectronic or die or chip or integrated or circuit or carrier or chuck)	USPAT	OR	ON	2004/11/15 18:08
L6	1	("6794225").PN.	USPAT	OR	OFF	2004/11/15 18:09
L7	1	("6673649").PN.	USPAT	OR	OFF	2004/11/15 18:09
L8	1	("6180696").PN.	USPAT	OR	OFF	2004/11/15 18:09
L9	936	438/46	USPAT	OR	ON	2004/11/15 18:09
L10	530	438/51	USPAT	OR	ON	2004/11/15 18:09
L11	306	438/55	USPAT	OR	ON	2004/11/15 18:09
L12	493	438/64	USPAT	OR	ON	2004/11/15 18:09
L13	2700	438/106	USPAT	OR	ON	2004/11/15 18:09
L14	1573	438/107	USPAT	OR	ON	2004/11/15 18:09
L15	1906	438/108	USPAT	OR	ON	2004/11/15 18:10
L16	754	438/110	USPAT	OR	ON	2004/11/15 18:10

11/15/04